

Bienvenido a O-Leading

O-Leading se esfuerza por ser su socio de solución integral en la cadena de suministro de EMS, incluido el diseño de PCB, la fabricación de PCB y el ensamblaje de PCB (PCBA). Proporcionamos algunas de las tecnologías de PCB más avanzadas, incluyendo PCB de HDI, PCB de múltiples capas, PCB rígido-flexibles. Podemos apoyar desde el prototipo de giro rápido hasta la producción media y en masa.

En general, nuestros clientes globales están muy impresionados con nuestros servicios: respuesta rápida, precio competitivo y compromiso de calidad. Brindar un servicio técnico más valioso y una solución general es la forma en que O-lidera.

Mirando hacia el futuro, O-Leading se concentrará en la innovación y el desarrollo de la tecnología de fabricación de productos electrónicos como siempre, y realizará esfuerzos persistentes en el servicio integral de PCB y PCBA para proporcionar servicios de primera clase y crear más valor para nuestros clientes.

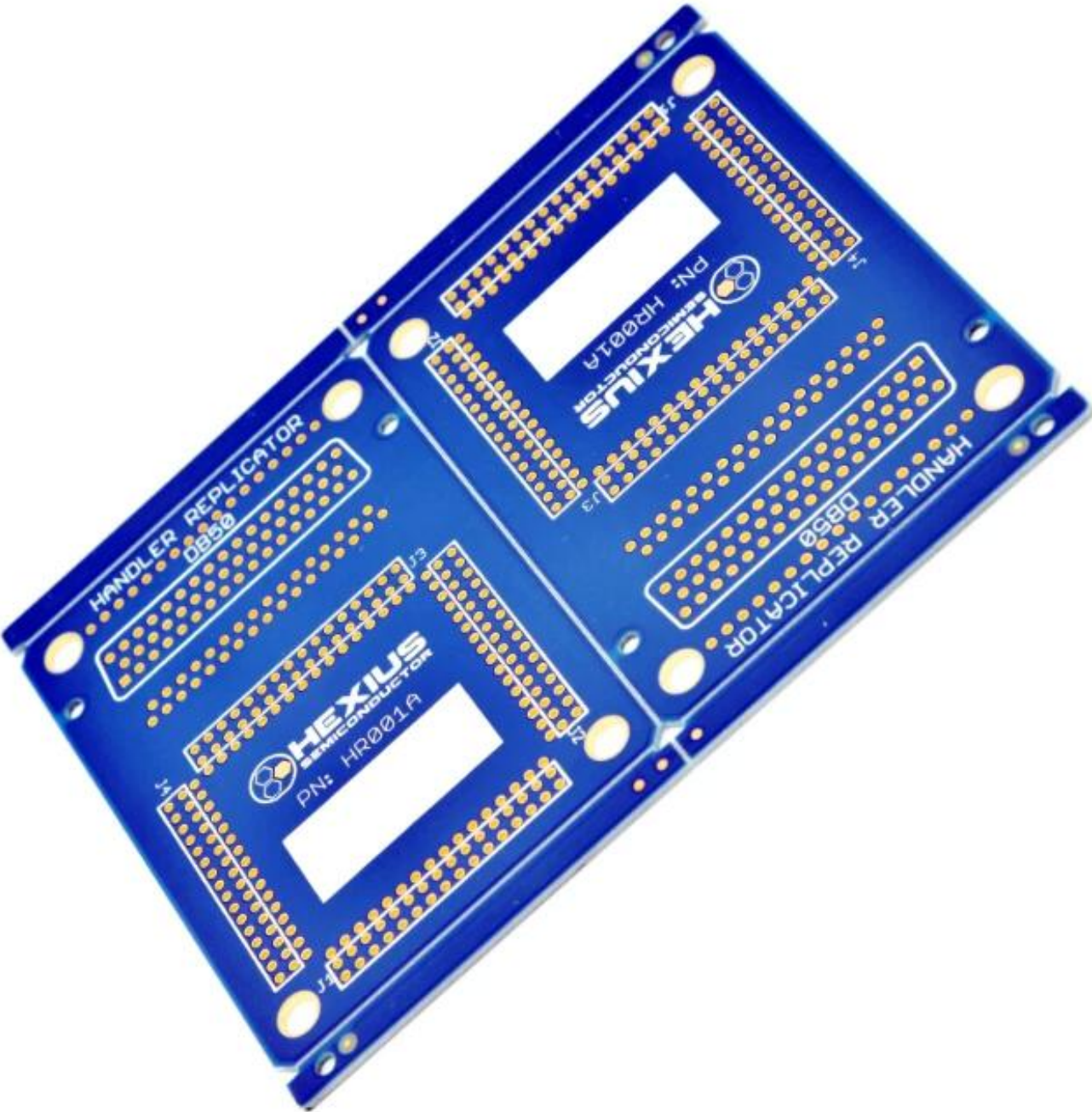
Descripción del producto

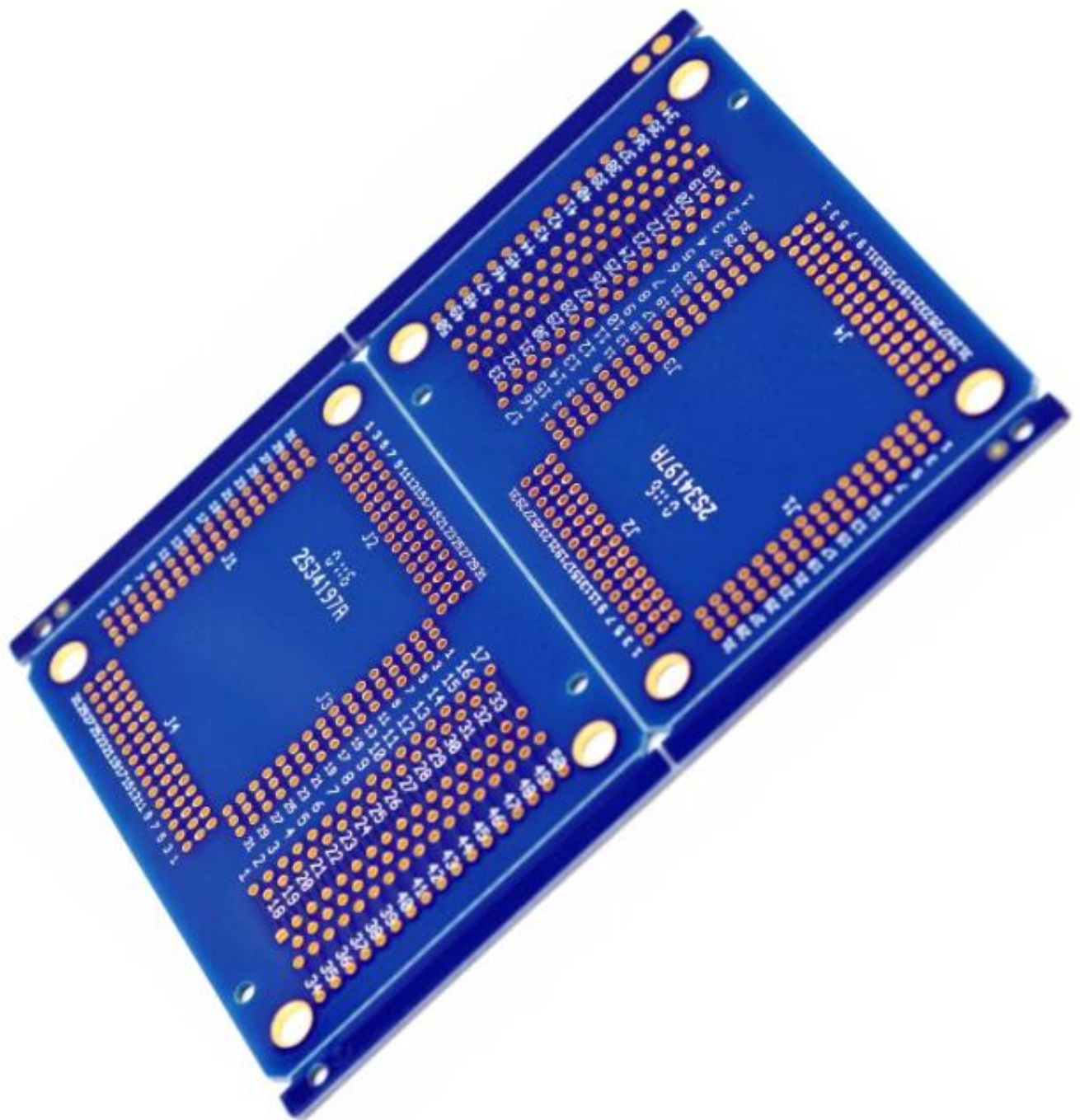
Lugar de origen	Guangdong China (continental)	Nombre de la marca	O-Leading
Material de base	FR-4` Aluminio	Espesor de cobre	0.5oz-5oz
Min. Tamaño del agujero	0.2mm	Min. Ancho de línea	0.2mm
Acabado de superficies	oro de inmersión, OSP, HASL sin plomo	Espesor del tablero	0.1-5mm
aplicable a	led, teléfono móvil, aires acondicionados, lavadoras	personaje	Control industrial pcb
certificados	ISO9001, UL, RoHS, SGS	Q / CTN	10PCS-100PCS
peso	0.01kg -5kg	MOQ	10 piezas
Número de modelo	fabricante del pcb de la Asamblea del pcb del banco del poder	Min. Espaciado entre líneas	0.2mm
color	azul, rojo, verde, negro. amarillo	precio	\$ 0.1- \$ 10
tipo de diseño	requisito del cliente	Talla	0.01m3-10m3

16 años de fabricación profesional de placas de circuito impreso de OEM

artículo	2014		2015 ~ 2016		2017 ~ 2018	
	Volumen	Muestra	Volumen	Muestra	Volumen	Muestra
Recuento de capas	32	42	38	44	42	48
Línea mínima / espacio (μm)	50/50	40/45	40/45	40/40	35/40	35/35
Min taladro diámetro (mm)	0,15	0,10	0,15	0,10	0,15	0,10
Relación de aspecto de PTH	14: 1	16: 1	16: 1	18: 1	18: 1	20: 1
N + C + N	4 + C + 4	5 + C + 5	5 + C + 5	6 + C + 6	5 + C + 5	6 + C + 6
Cualquier interconexión de capa	5 + 2 + 5	6 + 2 + 6	5 + 2 + 5	6 + 2 + 6	5 + 2 + 5	6 + 2 + 6
Placa de llenado a través de	SI	-	SI	-	SI	-
Min. espesor del núcleo (sin cobre) (μm)	50	40	40	30	40	30
Min. Diámetro del taladro láser (μm)	75	sesenta y cinco	sesenta y cinco	50	50	40

Vía en enterrado agujero / apilado vía	SI	-	SI	-	SI	-
Material	FR4, Megtron, Nelco, Rogers, Heavy Copper, etc.					
PCB condensador incorporado	SI	-	SI	-	SI	-
Proceso de superficie	HASL sin plomo, ENIG, OSP, plata de inmersión, estaño de inmersión, Oro dorado, chapado en dedo dorado, chapado en oro duro selectivo, Máscara de soldadura despegable, tinta de carbón					





fabricante de pcb en china

Nuestro equipo



Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT



Certificaciones





Test Report

No. SZXEC1900530401

Date: 30 Mar 2019

Page 1 of 6

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313.FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ

Date of Sample Received : 22 Mar 2019

Testing Period : 22 Mar 2019 - 30 Mar 2019

Test Requested : Selected test(s) as requested by client.

Test Method : Please refer to next page(s).

Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP) , Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) , and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina

Tina Fan
Approved Signatory



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Test Report

No. SZXEC1900530401

Date: 30 Mar 2019

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Test Results :

Test Part Description :

Specimen No.	SGS Sample ID	Description
SN1	SZX19-005304.001	Green"PCB"

Remarks :

- (1) 1 mg/kg = 1 ppm = 0.0001%
- (2) MDL = Method Detection Limit
- (3) ND = Not Detected (< MDL)
- (4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test item(s)	Limit	Unit	MDL	Q27
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	8
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (Cr(VI))	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tri bromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tri bromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND



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ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD

E490354

ROOM 1205, 12/F
TAI SANG BANK BLDG
130-132 DES VOEUS ROAD
CENTRAL, HONG KONG

Type	Cond Width		Cond Thk mic(mil)	SS/ DS/ DSO	Max		Max		Meets UL796 Class	C T DSR	C I
	Min	Min			Area	Solder	Oper	Flame			
	mm(in)	mm(in)			Diam	Limits	Temp	Temp			
Multilayer (mass laminate) printed wiring boards.											
O-LEADING-401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
O-LEADING-407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer printed wiring boards.											
O-LEADING-408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer printed wiring boards.											
O-LEADING-002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING-003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
O-LEADING-033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING-205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING-S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING-S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲	*
O-LEADING-S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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Shipping service



Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days

Capacidad de procesamiento

Capacidades de producción de PCB

Recuento de capas: 1 capa-32 capas

Espesor de cobre acabado: 1/3 oz-12 oz

Ancho mínimo de línea / espaciado interno: 3.0mil / 3.0mil

Ancho mínimo de línea / espaciado externo: 4.0mil / 4.0mil

Relación de aspecto máxima: 10: 1

Grosor del tablero: 0.2mm-5.0mm

Tamaño máximo del panel (pulgadas): 635 * 1500 mm

Tamaño mínimo del orificio perforado: 4mil

Tolerancia de agujero revestido: +/- 3mil

Blind / Vias enterradas (tipos All): Sí

Vía relleno (conductor, no conductor): Sí

Material base: FR-4, material libre de halógenos de alta Tg. FR-4, Rogers, base de aluminio,Poliimida,
Cobre pesado

Acabados superficiales: HASL, OSP, ENIG, HAL-LF, plata de inmersión,Inmersión de estaño, dedos dorados, tinta de carbono

Capacidades de producción SMT

Material de PCB: FR-4, CEM-1, CEM-3, placa a base de aluminio

Tamaño máximo de PCB: 510x460 mm

Tamaño mínimo de PCB: 50x50mm

Grosor de PCB: 0.5mm-4.5mm

Grosor del tablero: 0.5-4 mm

Tamaño mínimo de componentes: 0201

Componente de tamaño de chip estándar: 0603 y más grande

Altura máxima del componente: 15 mm

Paso de plomo mínimo: 0.3 mm

Paso mínimo de bola BGA: 0.4 mm

Precisión de colocación: +/- 0.03 mm